

MULTI-CHIP STACK AND METHOD OF FABRICATION
UTILIZING SELF-ALIGNING ELECTRICAL CONTACT ARRAY

Abstract of the Disclosure

5 A multi-chip stack structure and method of fabrication
are provided utilizing self-aligning electrical contact
arrays. Two or more arrays of interconnection contacts are
provided, with one array being a rough aligned contact
array, and a second array being a high bandwidth contact
10 array. The rough aligned contact array has larger contacts
and at least a portion thereof which melts at a
substantially lower temperature than the melting temperature
of the contacts of the high bandwidth contact array. By
positioning two integrated circuit chips in opposing
15 relation with the arrays mechanically aligned therebetween,
and applying heat to melt the contacts of the rough aligned
array, the two chips will rotate to align the respective
contacts of the high bandwidth contact arrays, thereby
achieving improved connection reliability between the
20 structures.